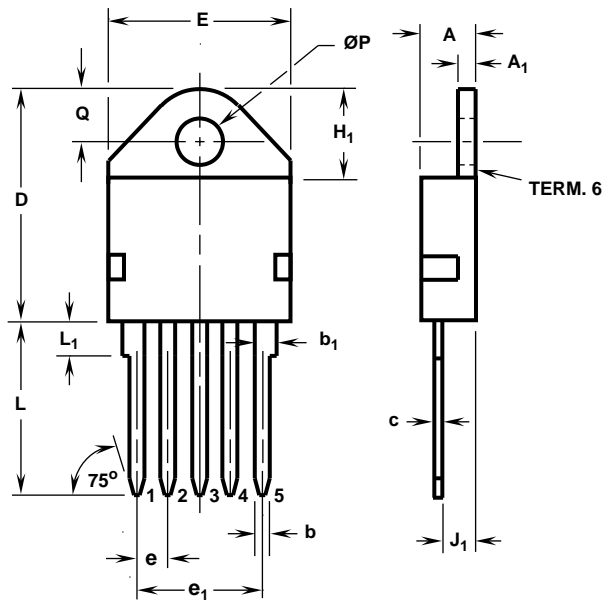


## Package Outlines

### Plastic Packages



#### MO-093AA

##### 5 LEAD JEDEC MO-093AA PLASTIC PACKAGE

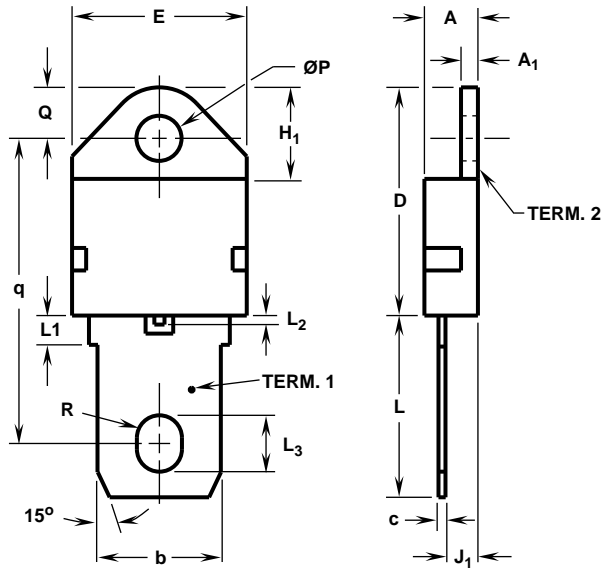
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.185	0.195	4.70	4.95	-
A <sub>1</sub>	0.058	0.062	1.48	1.57	-
b	0.049	0.053	1.25	1.34	3, 4, 5
b <sub>1</sub>	0.070	0.080	1.78	2.03	3, 4
c	0.018	0.022	0.46	0.55	3, 4, 5
D	0.800	0.820	20.32	20.82	-
E	0.615	0.625	15.63	15.87	2
e	0.110 TYP		2.80 TYP		7
e <sub>1</sub>	0.438 BSC		11.12 BSC		7
H <sub>1</sub>	-	0.330	-	8.38	-
J <sub>1</sub>	0.115	0.125	2.93	3.17	8
L	0.575	0.600	14.61	15.24	-
L <sub>1</sub>	-	0.130	-	3.30	3
ØP	0.159	0.163	4.04	4.14	-
Q	0.176	0.186	4.48	4.72	2

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC MO-093AA outline dated 2-90.
2. Tab outline optional within boundaries of dimensions E and Q.
3. Lead dimension and finish uncontrolled in L<sub>1</sub>.
4. Lead dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder coating.
6. Maximum radius of 0.050 inches (1.27mm) on all body edges and corners.
7. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
8. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
9. Controlling dimension: Inch.
10. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-218

#### SINGLE LEAD JEDEC STYLE TO-218 PLASTIC PACKAGE

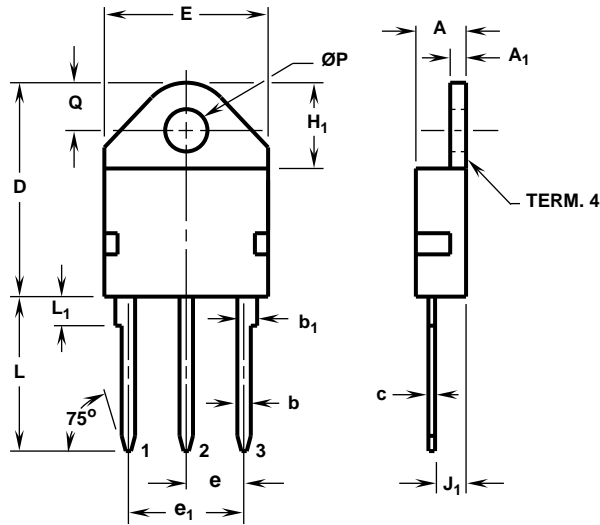
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.185	0.195	4.70	4.95	-
A <sub>1</sub>	0.058	0.062	1.48	1.57	-
b	0.433	0.443	11.00	11.25	-
c	0.018	0.022	0.46	0.55	-
D	0.800	0.820	20.32	20.82	-
E	0.615	0.625	15.63	15.87	2
H <sub>1</sub>	-	0.330	-	8.38	-
J <sub>1</sub>	0.115	0.125	2.93	3.17	4
L	0.635	0.655	16.13	16.63	-
L <sub>1</sub>	-	0.130	-	3.30	-
L <sub>2</sub>	-	0.034	-	0.86	-
L <sub>3</sub>	0.195	0.205	4.96	5.20	-
ØP	0.159	0.163	4.04	4.14	-
Q	0.176	0.186	4.48	4.72	2
q	1.080	1.088	27.44	27.63	-
R	0.078	0.082	1.99	2.08	-

#### NOTES:

1. No current JEDEC outline for this package.
2. Tab outline optional within boundaries of dimensions E and Q.
3. Maximum radius of 0.050 inches (1.27mm) on all body edges and corners.
4. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
5. Controlling dimension: Inch.
6. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-218AC

#### 3 LEAD JEDEC TO-218AC PLASTIC PACKAGE

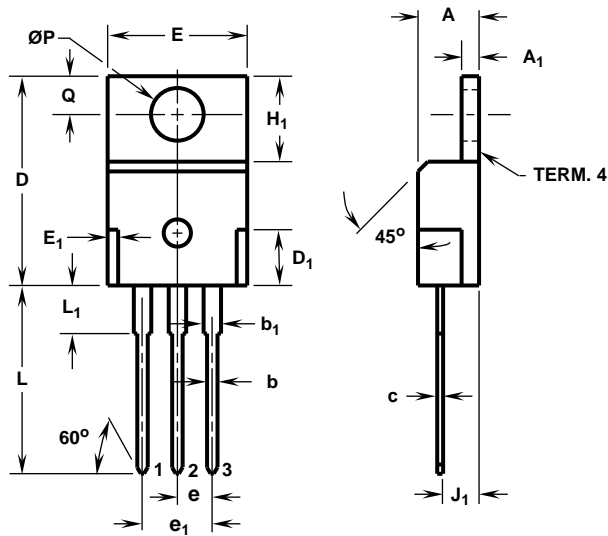
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.185	0.195	4.70	4.95	-
A <sub>1</sub>	0.058	0.062	1.48	1.57	-
b	0.049	0.053	1.25	1.34	3, 4, 5
b <sub>1</sub>	0.070	0.080	1.78	2.03	3, 4
c	0.018	0.022	0.46	0.55	3, 4, 5
D	0.800	0.820	20.32	20.82	-
E	0.615	0.625	15.63	15.87	2
e	0.219 TYP		5.56 TYP		7
e <sub>1</sub>	0.438 BSC		11.12 BSC		7
H <sub>1</sub>	-	0.330	-	8.38	-
J <sub>1</sub>	0.115	0.125	2.93	3.17	8
L	0.575	0.600	14.61	15.24	-
L <sub>1</sub>	-	0.130	-	3.30	3
ØP	0.159	0.163	4.04	4.14	-
Q	0.176	0.186	4.48	4.72	2

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. E of JEDEC TO-218AC outline dated 6-86.
2. Tab outline optional within boundaries of dimensions E and Q.
3. Lead dimension and finish uncontrolled in L<sub>1</sub>.
4. Lead dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder coating.
6. Maximum radius of 0.050 inches (1.27mm) on all body edges and corners.
7. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
8. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
9. Controlling dimension: Inch.
10. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-220AB

#### 3 LEAD JEDEC TO-220AB PLASTIC PACKAGE

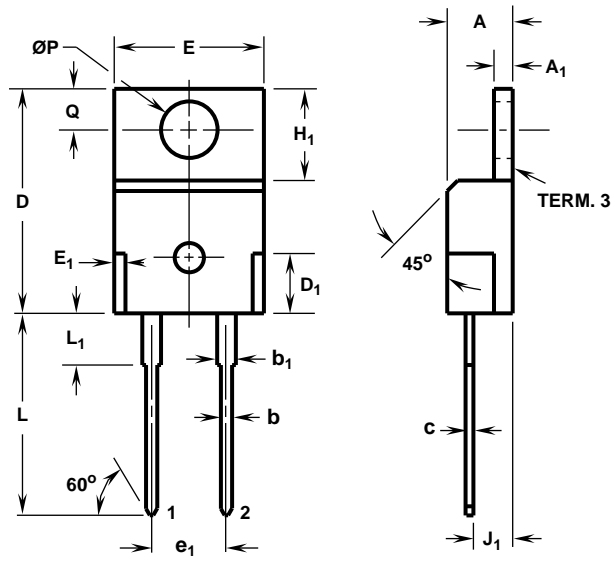
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	2, 3
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D <sub>1</sub>	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E <sub>1</sub>	-	0.030	-	0.76	-
e	0.100 TYP		2.54 TYP		5
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.130	0.150	3.31	3.81	2
$\varnothing P$	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. J of JEDEC TO-220AB outline dated 3-24-87.
2. Lead dimension and finish uncontrolled in  $L_1$ .
3. Lead dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-220AC

2 LEAD JEDEC TO-220AC PLASTIC PACKAGE  
(FOR RECTIFIERS ONLY)

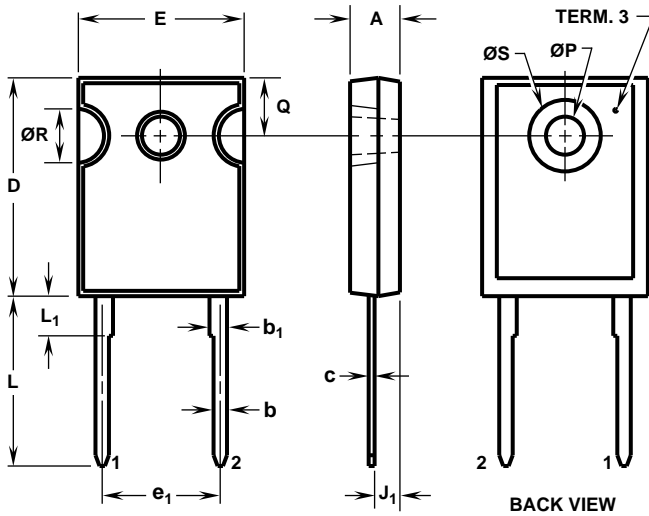
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	2, 3
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D <sub>1</sub>	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E <sub>1</sub>	-	0.030	-	0.76	-
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.130	0.150	3.31	3.81	2
ØP	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. J of JEDEC TO-220AC outline dated 3-24-87.
2. Lead dimension and finish uncontrolled in L<sub>1</sub>.
3. Lead dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 2 dated 12-93.

## Package Outlines

### Plastic Packages (Continued)



#### NOTES:

1. Lead dimension and finish uncontrolled in L<sub>1</sub>.
2. Lead dimension (without solder).
3. Add typically 0.002 inches (0.05mm) for solder coating.
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.

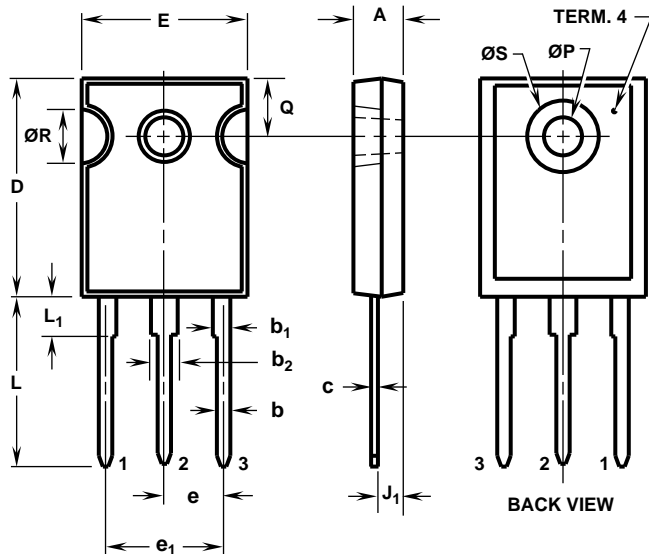
### TO-247

#### 2 LEAD JEDEC STYLE TO-247 PLASTIC PACKAGE (FOR RECTIFIERS ONLY)

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.180	0.190	4.58	4.82	-
b	0.046	0.051	1.17	1.29	2, 3
b <sub>1</sub>	0.060	0.070	1.53	1.77	1, 2
c	0.020	0.026	0.51	0.66	1, 2, 3
D	0.800	0.820	20.32	20.82	-
E	0.605	0.625	15.37	15.87	-
e <sub>1</sub>	0.438 BSC		11.12 BSC		4
J <sub>1</sub>	0.090	0.105	2.29	2.66	5
L	0.620	0.640	15.75	16.25	-
L <sub>1</sub>	0.145	0.155	3.69	3.93	1
ØP	0.138	0.144	3.51	3.65	-
Q	0.210	0.220	5.34	5.58	-
ØR	0.195	0.205	4.96	5.20	-
ØS	0.260	0.270	6.61	6.85	-

6. Controlling dimension: Inch.

7. Revision 2 dated 12-93.



#### NOTES:

1. Lead dimension and finish uncontrolled in L<sub>1</sub>.
2. Lead dimension (without solder).
3. Add typically 0.002 inches (0.05mm) for solder coating.
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.

### TO-247

#### 3 LEAD JEDEC STYLE TO-247 PLASTIC PACKAGE

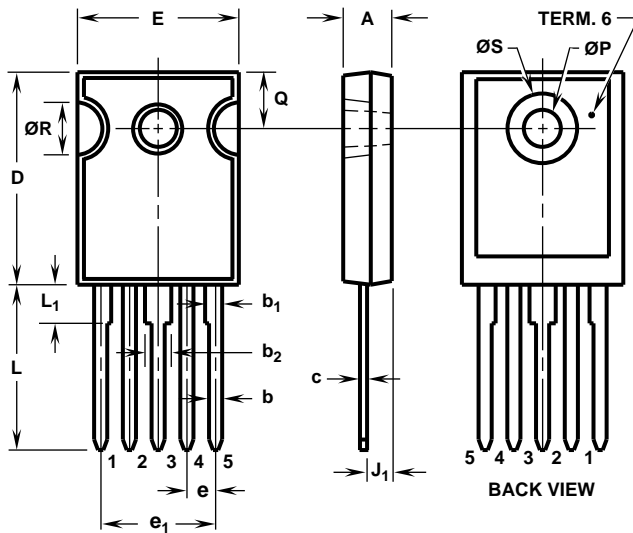
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.180	0.190	4.58	4.82	-
b	0.046	0.051	1.17	1.29	2, 3
b <sub>1</sub>	0.060	0.070	1.53	1.77	1, 2
b <sub>2</sub>	0.095	0.105	2.42	2.66	1, 2
c	0.020	0.026	0.51	0.66	1, 2, 3
D	0.800	0.820	20.32	20.82	-
E	0.605	0.625	15.37	15.87	-
e	0.219 TYP		5.56 TYP		4
e <sub>1</sub>	0.438 BSC		11.12 BSC		4
J <sub>1</sub>	0.090	0.105	2.29	2.66	5
L	0.620	0.640	15.75	16.25	-
L <sub>1</sub>	0.145	0.155	3.69	3.93	1
ØP	0.138	0.144	3.51	3.65	-
Q	0.210	0.220	5.34	5.58	-
ØR	0.195	0.205	4.96	5.20	-
ØS	0.260	0.270	6.61	6.85	-

6. Controlling dimension: Inch.

7. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-247

#### 5 LEAD JEDEC STYLE TO-247 PLASTIC PACKAGE

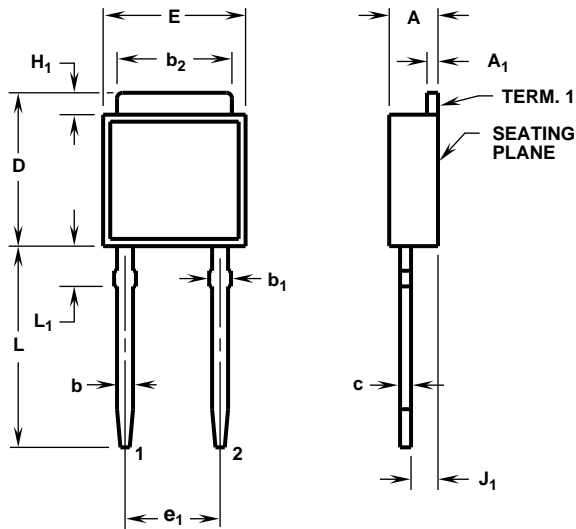
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.180	0.190	4.58	4.82	-
b	0.046	0.051	1.17	1.29	2, 3
b <sub>1</sub>	0.060	0.070	1.53	1.77	1, 2
b <sub>2</sub>	0.095	0.105	2.42	2.66	1, 2
c	0.020	0.026	0.51	0.66	1, 2, 3
D	0.800	0.820	20.32	20.82	-
E	0.605	0.625	15.37	15.87	-
e	0.110 TYP		2.79 TYP		4
e <sub>1</sub>	0.438 BSC		11.12 BSC		4
J <sub>1</sub>	0.090	0.105	2.29	2.66	5
L	0.620	0.640	15.75	16.25	-
L <sub>1</sub>	0.145	0.155	3.69	3.93	1
ØP	0.138	0.144	3.51	3.65	-
Q	0.210	0.220	5.34	5.58	-
ØR	0.195	0.205	4.96	5.20	-
ØS	0.260	0.270	6.61	6.85	-

#### NOTES:

1. Lead dimension and finish uncontrolled in L<sub>1</sub>.
2. Lead dimension (without solder).
3. Add typically 0.002 inches (0.05mm) for solder coating.
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
6. Controlling dimension: Inch.
7. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



#### TO-251

#### 2 LEAD JEDEC STYLE TO-251 PLASTIC PACKAGE (FOR RECTIFIERS ONLY)

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A <sub>1</sub>	0.018	0.022	0.46	0.55	3, 4
b	0.028	0.032	0.72	0.81	3, 4
b <sub>1</sub>	0.033	0.040	0.84	1.01	3
b <sub>2</sub>	0.205	0.215	5.21	5.46	3, 4
c	0.018	0.022	0.46	0.55	3, 4
D	0.270	0.290	6.86	7.36	-
E	0.250	0.265	6.35	6.73	-
e <sub>1</sub>	0.180 BSC		4.57 BSC		5
H <sub>1</sub>	0.035	0.045	0.89	1.14	-
J <sub>1</sub>	0.040	0.045	1.02	1.14	6
L	0.355	0.375	9.02	9.52	-
L <sub>1</sub>	0.075	0.090	1.91	2.28	2

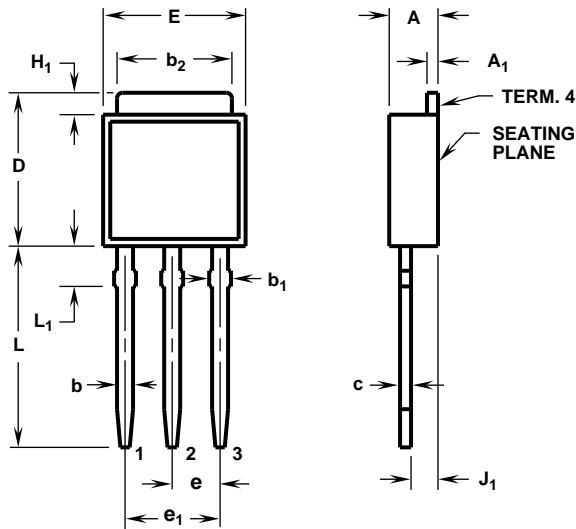
#### NOTES:

1. No current JEDEC outline for this package.
2. Solder finish uncontrolled.
3. Dimension (without solder).
4. Add typically 0.0006 inches (0.015mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 1 dated 6-93.



## Package Outlines

### Plastic Packages (Continued)



### TO-251AA

#### 3 LEAD JEDEC TO-251AA PLASTIC PACKAGE

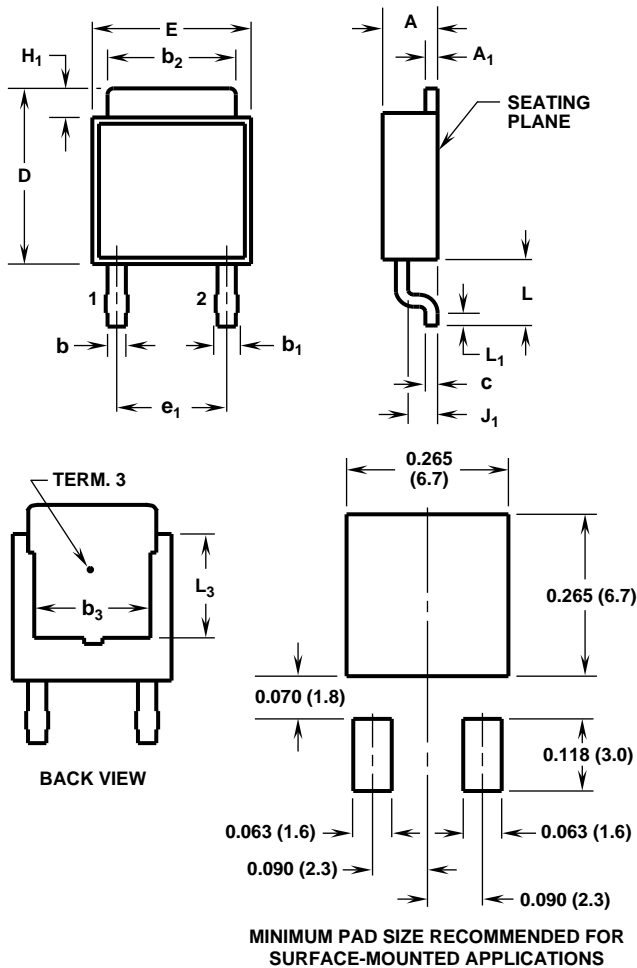
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A <sub>1</sub>	0.018	0.022	0.46	0.55	3, 4
b	0.028	0.032	0.72	0.81	3, 4
b <sub>1</sub>	0.033	0.040	0.84	1.01	3
b <sub>2</sub>	0.205	0.215	5.21	5.46	3, 4
c	0.018	0.022	0.46	0.55	3, 4
D	0.270	0.290	6.86	7.36	-
E	0.250	0.265	6.35	6.73	-
e	0.090 TYP		2.28 TYP		5
e <sub>1</sub>	0.180 BSC		4.57 BSC		5
H <sub>1</sub>	0.035	0.045	0.89	1.14	-
J <sub>1</sub>	0.040	0.045	1.02	1.14	6
L	0.355	0.375	9.02	9.52	-
L <sub>1</sub>	0.075	0.090	1.91	2.28	2

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. C of JEDEC TO-251AA outline dated 9-88.
2. Solder finish uncontrolled.
3. Dimension (without solder).
4. Add typically 0.0006 inches (0.015mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 1 dated 1-93.

## Package Outlines

### Plastic Packages (Continued)



### TO-252

#### 2 LEAD JEDEC STYLE TO-252 PLASTIC PACKAGE (FOR RECTIFIERS ONLY)

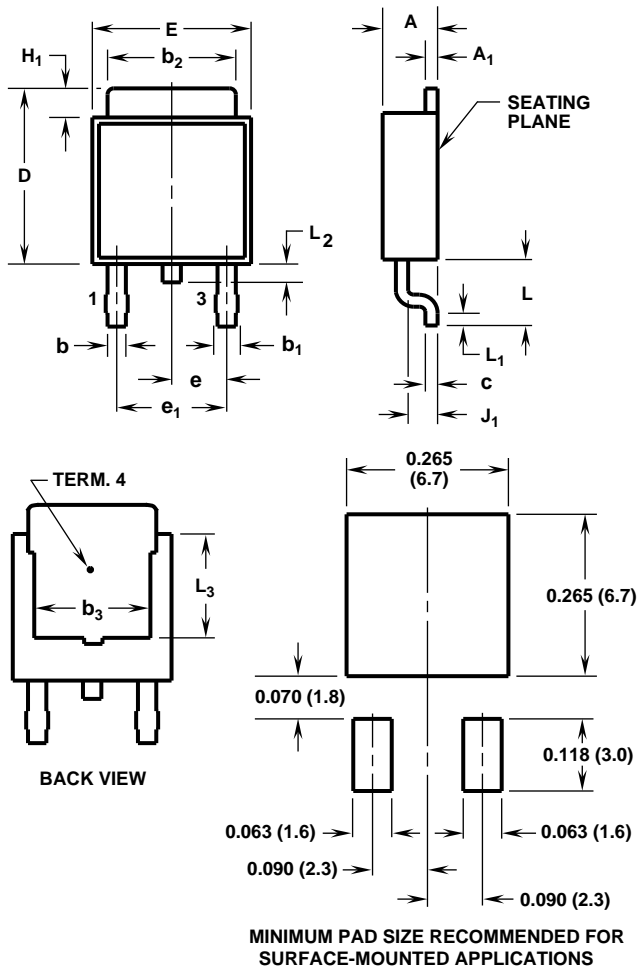
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A <sub>1</sub>	0.018	0.022	0.46	0.55	4, 5
b	0.028	0.032	0.72	0.81	4, 5
b <sub>1</sub>	0.033	0.040	0.84	1.01	4
b <sub>2</sub>	0.205	0.215	5.21	5.46	4, 5
b <sub>3</sub>	0.190	-	4.83	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.270	0.290	6.86	7.36	-
E	0.250	0.265	6.35	6.73	-
e <sub>1</sub>	0.180 BSC		4.57 BSC		7
H <sub>1</sub>	0.035	0.045	0.89	1.14	-
J <sub>1</sub>	0.040	0.045	1.02	1.14	-
L	0.100	0.115	2.54	2.92	-
L <sub>1</sub>	0.020	-	0.51	-	4, 6
L <sub>3</sub>	0.170	-	4.32	-	2

#### NOTES:

1. No current JEDEC outline for this package.
2. L<sub>3</sub> and b<sub>3</sub> dimensions establish a minimum mounting surface for terminal 3.
3. Solder finish uncontrolled.
4. Dimension (without solder).
5. Add typically 0.0006 inches (0.015mm) for solder coating.
6. L<sub>1</sub> is the terminal length for soldering.
7. Position of lead to be measured 0.090 inches (2.28mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 2 dated 3-94.

## Package Outlines

### Plastic Packages (Continued)



### TO-252AA

#### 2 LEAD JEDEC TO-252AA PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A <sub>1</sub>	0.018	0.022	0.46	0.55	4, 5
b	0.028	0.032	0.72	0.81	4, 5
b <sub>1</sub>	0.033	0.040	0.84	1.01	4
b <sub>2</sub>	0.205	0.215	5.21	5.46	4, 5
b <sub>3</sub>	0.190	-	4.83	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.270	0.290	6.86	7.36	-
E	0.250	0.265	6.35	6.73	-
e	0.090 TYP		2.28 TYP		7
e <sub>1</sub>	0.180 BSC		4.57 BSC		7
H <sub>1</sub>	0.035	0.045	0.89	1.14	-
J <sub>1</sub>	0.040	0.045	1.02	1.14	-
L	0.100	0.115	2.54	2.92	-
L <sub>1</sub>	0.020	-	0.51	-	4, 6
L <sub>2</sub>	0.025	0.040	0.64	1.01	-
L <sub>3</sub>	0.170	-	4.32	-	2

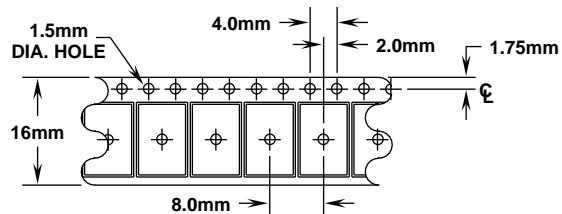
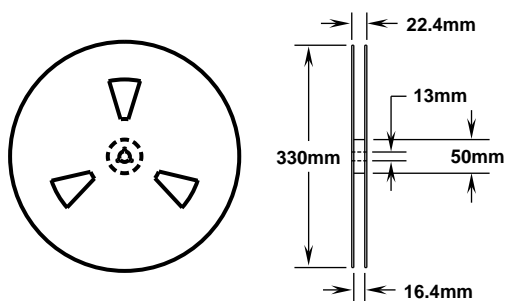
#### NOTES:

1. These dimensions are within allowable dimensions of Rev. B of JEDEC TO-252AA outline dated 9-88.
2. L<sub>3</sub> and b<sub>3</sub> dimensions establish a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled.
4. Dimension (without solder).
5. Add typically 0.0006 inches (0.015mm) for solder coating.
6. L<sub>1</sub> is the terminal length for soldering.
7. Position of lead to be measured 0.090 inches (2.28mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 4 dated 4-94.

## Package Outlines

### Plastic Packages (Continued)

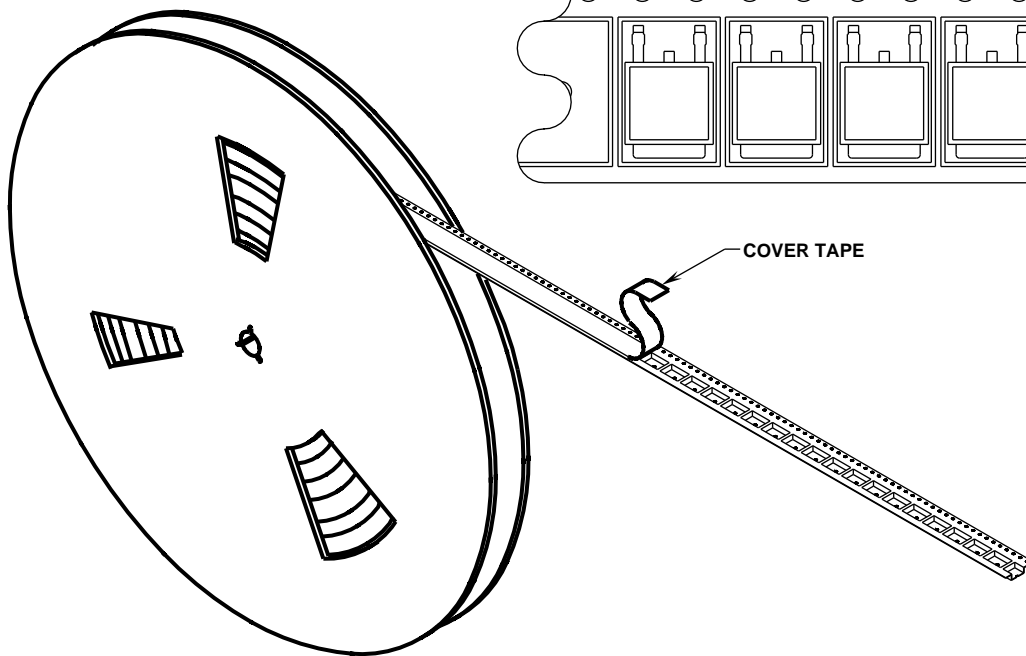
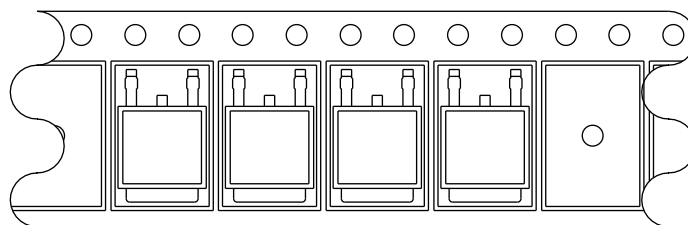
#### TO-252AA 16mm TAPE AND REEL



#### GENERAL INFORMATION

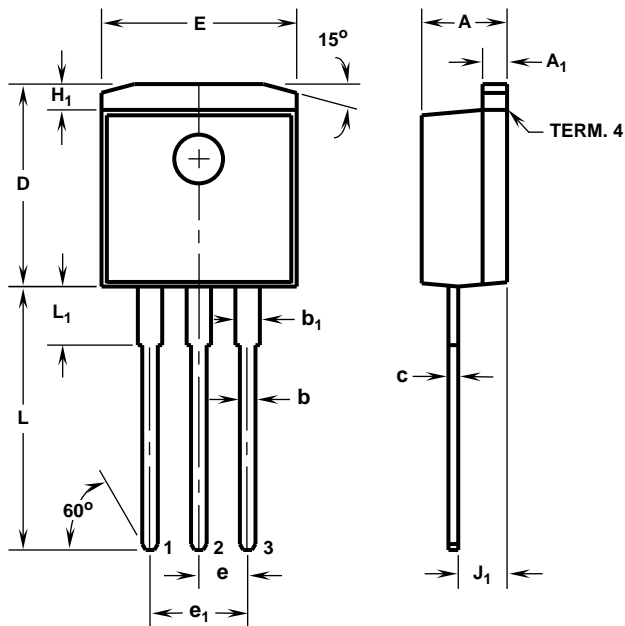
1. USE "9A" SUFFIX ON PART NUMBER.
2. 2500 PIECES PER REEL.
3. ORDER IN MULTIPLES OF FULL REELS ONLY.
4. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

USER DIRECTION OF FEED



## Package Outlines

### Plastic Packages (Continued)



### TO-262AA

#### 3 LEAD JEDEC TO-262AA PLASTIC PACKAGE

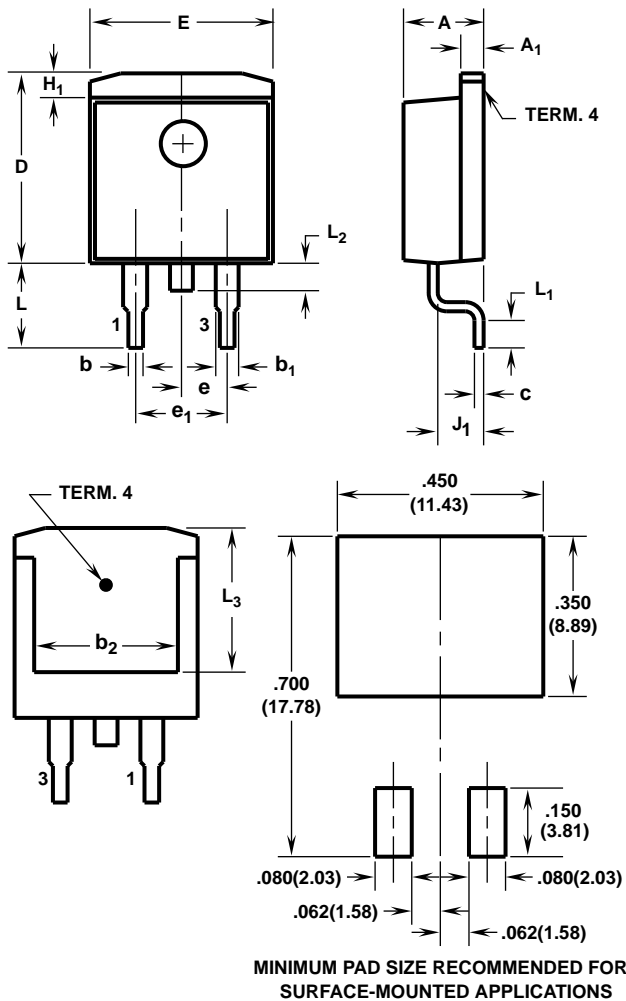
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	2, 3
c	0.018	0.022	0.46	0.55	2, 3, 4
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e	0.100 TYP		2.54 TYP		5
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.045	0.055	1.15	1.39	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.110	0.130	2.80	3.30	2

#### NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC TO-262AA outline dated 6-90.
2. Lead dimension and finish uncontrolled in L<sub>1</sub>.
3. Lead dimension (without solder).
4. Add typically 0.0006 inches (0.015mm) for solder plating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 3 dated 2-95.

## Package Outlines

### Plastic Packages (Continued)



### TO-263AB

#### 2 LEAD JEDEC TO-263AB PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	4, 5
b	0.030	0.034	0.77	0.86	4, 5
b <sub>1</sub>	0.045	0.055	1.15	1.39	4
b <sub>2</sub>	0.310	-	7.88	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e	0.100 TYP		2.54 TYP		7
e <sub>1</sub>	0.200 BSC		5.08 BSC		7
H <sub>1</sub>	0.045	0.055	1.15	1.39	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	-
L	0.175	0.195	4.45	4.95	-
L <sub>1</sub>	0.090	0.110	2.29	2.79	4, 6
L <sub>2</sub>	0.050	0.070	1.27	1.77	-
L <sub>3</sub>	0.315	-	8.01	-	2

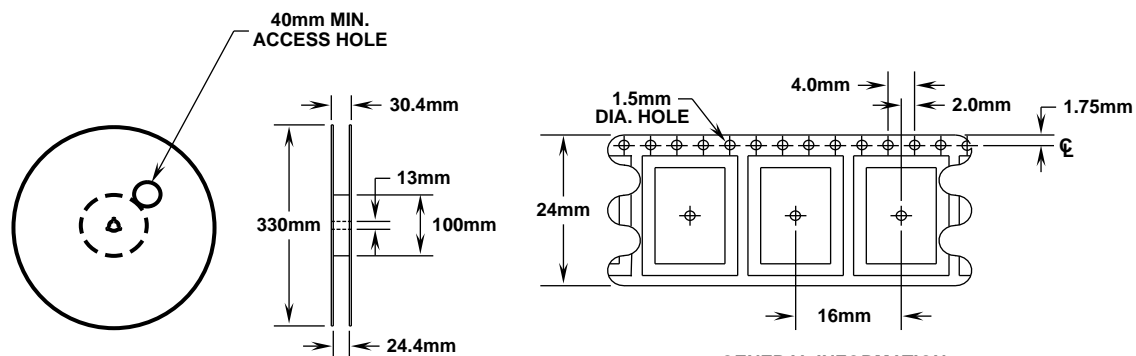
#### NOTES:

1. These dimensions are within allowable dimensions of Rev. C of JEDEC TO-263AB outline dated 2-92.
2. L<sub>3</sub> and b<sub>2</sub> dimensions established a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled.
4. Dimension (without solder).
5. Add typically 0.0006 inches (0.015mm) for solder plating.
6. L<sub>1</sub> is the terminal length for soldering.
7. Position of lead to be measured 0.120 inches (3.05mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 5 dated 4-5-95.

## Package Outlines

### Plastic Packages (Continued)

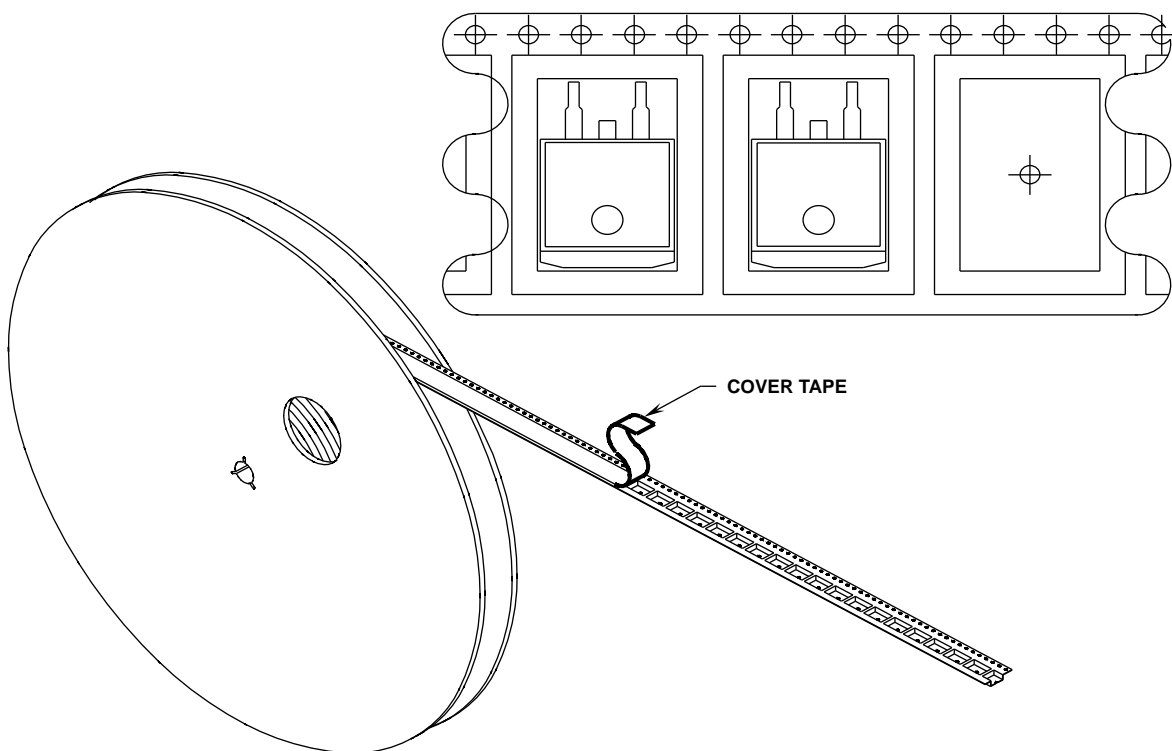
#### TO-263AB 24mm TAPE AND REEL



#### GENERAL INFORMATION

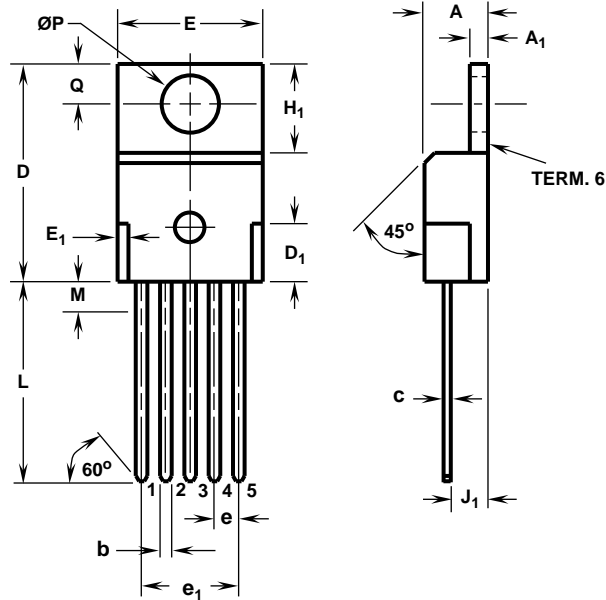
1. USE "9A" SUFFIX ON PART NUMBER.
2. 800 PIECES PER REEL.
3. ORDER IN MULTIPLES OF FULL REELS ONLY.
4. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

USER DIRECTION OF FEED



## Package Outlines

### Plastic Packages (Continued)



#### TS-001AA

##### 5 LEAD JEDEC TS-001AA PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D <sub>1</sub>	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E <sub>1</sub>	-	0.030	-	0.76	-
e	0.067 TYP		1.70 TYP		5
e <sub>1</sub>	0.268 BSC		6.80 BSC		5
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
M	0.130	0.150	3.31	3.81	2
ØP	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

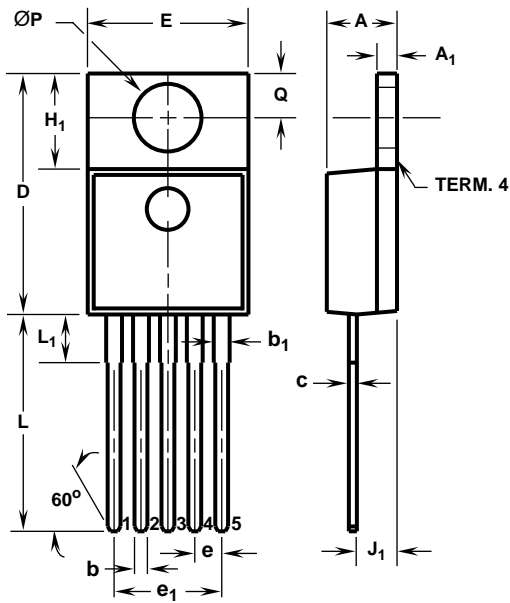
#### NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC TS-001AA outline dated 8-89.
2. Lead finish uncontrolled in zone M.
3. Lead dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 3 dated 12-93.



## Package Outlines

### Plastic Packages (Continued)



**TS-001AA (ALTERNATE VERSION)**  
**5 LEAD JEDEC TS-001AA PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	2, 3
b <sub>1</sub>	0.031	0.041	0.79	1.04	2
c	0.018	0.022	0.46	0.55	2, 3
D	0.590	0.610	14.99	15.49	-
E	0.395	0.405	10.04	10.28	-
e	0.067 TYP		1.70 TYP		4
e <sub>1</sub>	0.268 BSC		6.80 BSC		4
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	5
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.110	0.130	2.80	3.30	-
ØP	0.149	0.153	3.79	3.88	-
Q	0.105	0.115	2.66	2.92	-

**NOTES:**

1. These dimensions are within allowable dimensions of Rev. A of JEDEC TS-001AA outline dated 8-89.
2. Lead dimension (without solder).
3. Add typically 0.0006 inches (0.015mm) for solder plating.
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
6. Controlling dimension: Inch.
7. Revision 1 dated 12-20-94.